

LAW OFFICES OF JEROME J. NORRIS  
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☐ URGENT    ☐ FOR REVIEW    ☐ PLEASE COMMENT    ☐ PLEASE REPLY    ☐ PLEASE RECYCLE

## NOTES/COMMENTS:

Per our conversation of even date, enclosed is copy of the patent application 98 7501 US 01  
 filed September 16, 2002

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P 7501 US 01

In re the application of: )  
 Ramachandran et al. ) Group Art: 1746  
 Serial No.: 09/204,706 ) Examiner: A. Olsen  
 Filing Date: December 3, 1998 )  
 Title: REMOVAL OF POST-RIE POLYMER )  
 ON Al/Cu METAL LINE )

#230-NE  
3/25/03  
mwAMENDMENT UNDER 37 C.F.R. §1.116

Honorable Commissioner of Patents and Trademarks  
 Washington, D.C. 20231

Sir:

In reply to the Office Action mailed September 10, 2002,  
 which rejected the claims in the above-identified patent  
 application, applicants respectfully request reconsideration,  
 based upon the amendments hereinafter set forth.

IN THE CLAIMS:

~~13~~ (5th Amendment) In a metal etch tool for removing  
 post-RIE polymer rails formed on a Al/Cu metal line of a  
 semiconductor structure, the improvement comprising:

[I] an integrated metal etch tool interfaceable with:

a) strip chamber means [for water only plasma] to strip  
 photo-resist of a semiconductor composite structure subsequent  
 to a RIE to limit thickness of sidewall polymer rails;

b) vacuum chamber means to chemically modify sidewall  
 polymer rails [by supplying a mixture of an etching gas/acid  
 neutralizing gas of] with HF/NH<sub>3</sub> to form a water soluble

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